

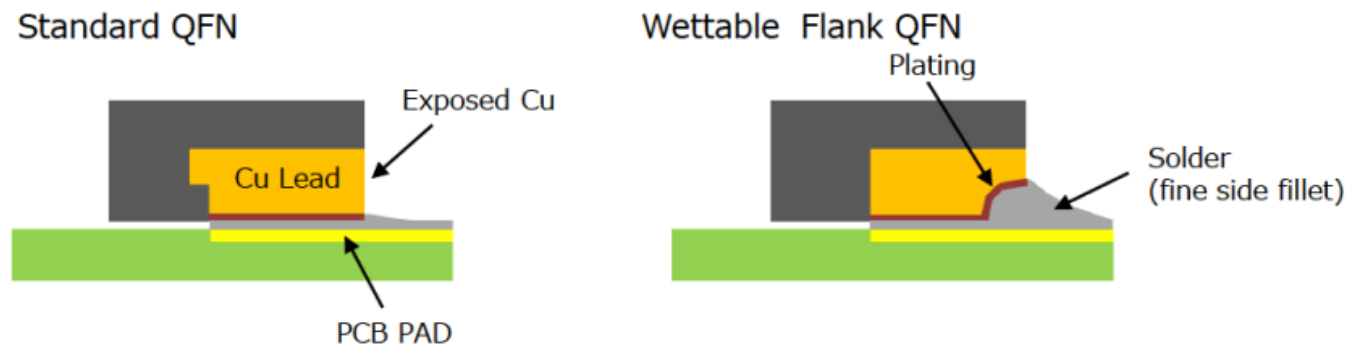
Wettable Flank Package

Background

- To improve the safety and reliability of vehicles, automakers require 100% automatic visual inspection (AVI) after assembly.
- With the QFN package, it is difficult to determine if the package is properly soldered to the printed circuit board (PCB) because there are no easily visible solderable pins / terminals or exposed pins / terminals.
- The problem with the QFN package is that there are exposed copper foils that correspond to the terminals, but these are prone to oxidation and reduce the side solder wetting properties.

⇒ Solution : Wettable Flank

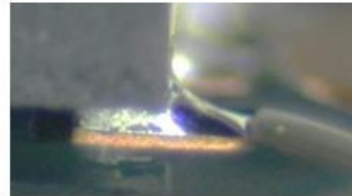
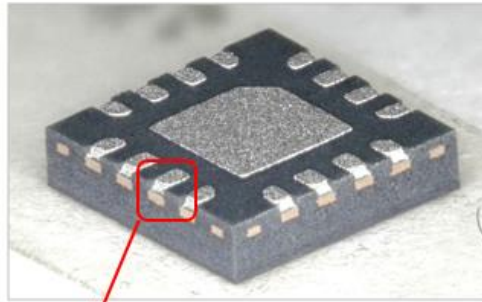
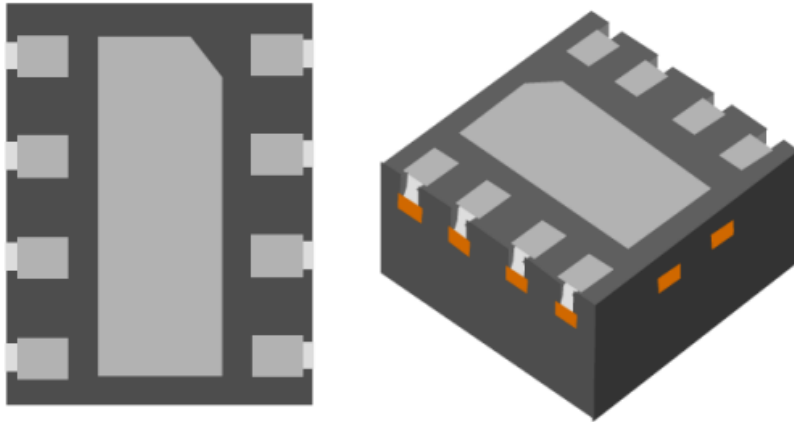
Structural Comparison (Standard vs Wettable Flank)



Wettable Flank Package

Representative Structure

■ Step Lead Type



■ Dimple Type

Under Development

